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To the Honorable Assistant Secretary and Commissioner of Patents and Trademarks: Please record the attached original document(s) or copy(ies) thereof.

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 Yoshihiko TAKANO, Masanori NAGAO, Minoru TACHIKI,
 Hiroshi KAWARADA, Hitoshi UMEZAWA, Kensaku
 KOBAYASHI

Additional name(s) of conveying party(ies) attached? NO

2. Name and address of receiving party(ies):
 Name: NATIONAL INSTITUTE FOR MATERIALS
 SCIENCE
 Street Address: 2-1, Sengen 1-chome, Tsukuba-shi, Ibaraki,
 Japan

3. Nature of conveyance:
 Assignment Merger
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Execution Date: August 18, 2005

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4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.
11/133,269, filed May 20, 2005

B. Patent No.
 , issued

Additional numbers attached? NO

5. Name and address of party to whom correspondence concerning document should be mailed:
 Name: WENDEROTH, LIND & PONACK, L.L.P.
Attn: Warren M. Cheek, Jr., Esq.
 Street Address: 2033 K Street, N.W., Suite 800
 City: Washington, State: DC ZIP: 20006-1021

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41). \$40.00
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Warren M. Cheek, Jr., Reg. No.33,367 August 29, 2005
 Name of Person Signing Signature Date

Total number of pages including cover sheet: 3

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PATENT
REEL: 016941 FRAME: 0053

ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned

Insert Name(s)
of Inventor(s)

Yoshihiko TAKANO, Masanori NAGAO, Minoru TACHIKI, Hiroshi KAWARADA, Hitoshi UMEZAWA,

Kensaku KOBAYASHI

Insert Name(s)
of Assignee(s)

the undersigned hereby sell(s) and assign(s) to

Address

NATIONAL INSTITUTE FOR MATERIALS SCIENCE

of 2-1, Sengen 1-chome, Tsukuba-shi, Ibaraki, Japan

Title of
Invention

(hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as

SUPERCONDUCTIVITY IN BORON-DOPED DIAMOND THIN FILM

for which an application for patent in the United States has been executed by the undersigned

Date of Signing
of Application

on _____

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the firm of WENDEROTH, LIND & PONACK, L.L.P., 2033 K Street, N.W., Suite 800, Washington, D.C. 20006-1021, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordal of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date August 18, 2005

Yoshihiko Takano
Yoshihiko TAKANO

Date August 18, 2005

Masanori Nagao
Masanori NAGAO

Date August 18, 2005

Minoru Tachiki
Minoru TACHIKI

Date August 18, 2005

Hiroshi Kawarada
Hiroshi KAWARADA

Date August 18, 2005

Hitoshi Umezawa
Hitoshi UMEZAWA

Date August 18, 2005

Kensaku Kobayashi
Kensaku KOBAYASHI

(This assignment should preferably be acknowledged before a United States Consul. If not, then the execution by the Inventor(s) should be witnessed by at least two witnesses who sign here.)

Witness _____

Witness _____

The above application may be more particularly identified as follows:

U.S. Application Serial No. NEW Filing Date May 20, 2005

Applicant Reference Number 04-F-030USNP/SY Atty Docket No. 2005_0845A

Title of Invention SUPERCONDUCTIVITY IN BORON-DOPED DIAMOND THIN FILM